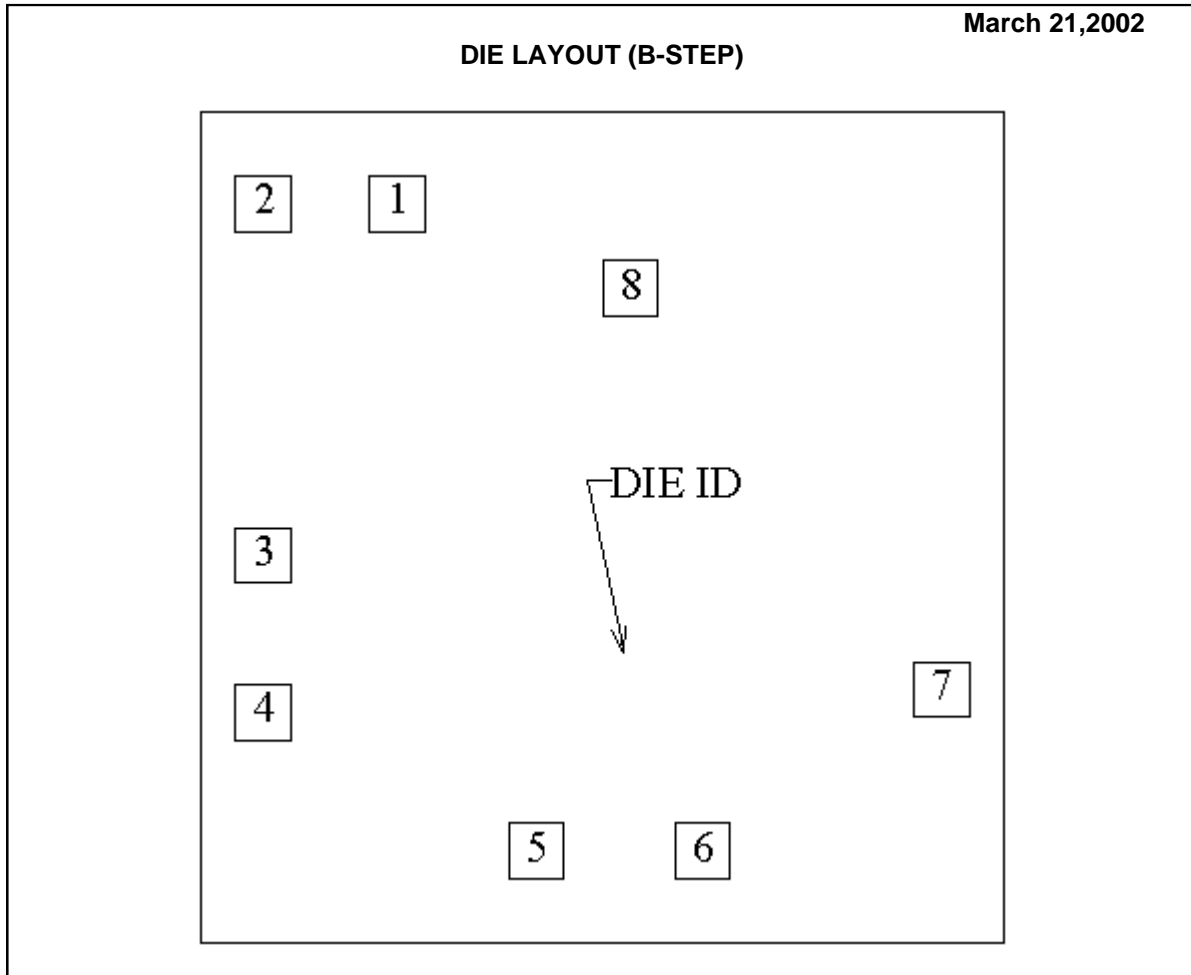


LM555 MDC MWC
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DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	555	Bond Pad Opening Size (min)	91 μ m x 91 μ m
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1321 μ m x 1372 μ m 52mils x 54mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	220 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
GND	1	-338	533	91	x	91
TRIGGER	2	-559	533	91	x	91
OUTPUT	3	-559	-46	91	x	91
RESET	4	-559	-305	91	x	91
CONT VOLT	5	-109	-533	91	x	91
THRESHOLD	6	165	-533	91	x	91
DISCHARGE	7	559	-267	91	x	91
VCC+	8	46	394	91	x	91

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